Press Publisher | IMPACT secretariat / Taiwan Printed Circuit Association
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**IMPACT Conference 2010-Call for Paper**
**High Exposure by Collected in IEEE Xplore**

Being the most remarkable international technology conference in packaging, thermal, assembly and PCB areas, IMPACT 2010 has launched into call for paper till June 11. Please seize the opportunity to join the international event.

Following the four-year experiences and achievements, the 5th International Microsystems, Packaging, Assembly and Circuits Technology Conference in conjunction with TPCA Show 2010 will take place in Taipei Nangang Exhibition Center during October 20 to 22, 2010. In the past two years, IMPACT got the excellent records with more than 190 papers presented in the conference and attendees from 17 nations. With the theme of “Embrace IMPACT, Create Possibilities”, IMPACT is striving to work out the advanced paper scope and reward policy to attract outstanding papers from the world. It aims to become the representative international technology conference of packaging, thermal, assembly and PCB field both in industry and academic areas. In the meantime, all IMPACT papers would be referred in IEEE Xplore with high exposure rate.

Taking the advantage of resources from industry, academic and research institute, IMPACT is organized by IEEE CPMT-Taipei, IMAPS-Taiwan, ITRI, National Tsing Hua University, SIPO and TPCA and co-organized by TTMA, I-Shou University, SMTA and Taiwan PCB Institute. The paper scope would be divided in to Microsystems, Packaging, Thermal Technology and PCB & Assembly Technology. In the former scope, it includes Advanced Packaging, Modeling & Simulation, interconnection & Nanotechnology and Thermal Management. Especially, 3D IC, TSV Connection and LED Packaging are the popular items in 2010. In the latter scope, Materials & Process, Inspection & Reliability, Electrochemical Processing and HDI are the main items. In addition, papers relative to Green Technology and Mechatronics & Automation are welcome to join IMPACT.

The award policy is implemented since the 1st IMPACT. Outstanding Paper Award and Best Student Paper Award in Packaging and PCB areas accordingly will be honored in award ceremony. In order to encourage students to contribute into PCB industry after graduation, the co-organizer, Taiwan PCB Institute sponsors the Outstanding PCB Thesis Award with a great prize.

Now, IMPACT is in the step of call for paper. The deadline of abstract submission is June 11, 2010. Besides that, IMPACT arranges varied sponsorships which go with high advertisement benefits. Welcome papers and sponsors to join this international event.

More information about IMPACT 2010, please refer to the conference website, [www.impact.org.tw](http://www.impact.org.tw), or contact with secretariat, MS. Sylvia Yang(service@impact.org.tw).
IMPACT 2010-國際構裝、熱管理、電路板技術研討會

論文收錄 IEEE Xplore 強力邀稿中

電子構裝領域最具代表性國際研討會，也是國際電子構裝產業的武林大會 - IMPACT 2010，在此廣邀英雄帖，邀請各界參加年度技術競技盛會!!

承襲四年的舉辦成果與各界的熱烈迴響，第五屆構裝暨電路板技術研討會(IMPACT)，今年同樣配合台灣電路板國際展覽會(TPCA Show)檔期，於 10 月 20 日至 22 日在台北南港展覽館舉行。連續兩年發表論文突破 190 篇的紀錄、同時與會作者及學員來自 17 個以上的國家，今年 IMPACT 以「Embrace IMPACT, Create Possibilities」為主題，積極規劃先進議題及優秀論文獎勵辦法，企圖讓 IMPACT 在構裝領域的代表性，兼具產業實務研究與學術前瞻成果。此外，凡 IMPACT 錄取之論文，將永久收錄 IEEE Xplore，加惠作者論文發表之國際曝光率。

IMPACT 向來以集結產、學、研各大單位資源著稱，由 IEEE CPMT-Taipei、IMAPS-Taiwan、工研院(ITRI)、清華大學、半導體辦公室與台灣電路板協會(TPCA)共同主辦，並承蒙熱管理協會(TTMA)、義守大學、表面黏著技術協會(SMTA)、PCB 產業學院協辦，本年度邀稿範疇分為 Microsystems & Packaging Technology 與 PCB & Assembly Technology 兩大項目。在構裝方面，除了 Advanced Packaging、Modeling & Simulation、Interconnection & Nanotechnology、Thermal Management、3D IC 、TSV Connection 與 LED Packaging 為今年的重點項目；在 PCB 領域則涵蓋了 Materials & Process、Inspection & Reliability、Electrochemical processing 與 HDI 等技術，有別於往年，此屆則歡迎各項符合綠色趨勢要求的技術與 Mechatronics & Automation 領域之論文共襄盛舉。

延續 IMPACT 傳統，經過嚴格評審過程，大會特別設置 Outstanding Paper Award 與 Best Student Paper Award，分別在構裝與電路板領域選出產業與學界優秀論文獎，此外，來自協辦單位台灣電路板產業學院的支持，為鼓勵國內莘莘學子投入 PCB 領域的研究工作，自去年起增設「PCB 優秀論文獎」，最高獎金高達新台幣六萬元。

IMPACT 論文摘要於 2010 年 6 月 11 日截稿，大會已在國內外展開強烈邀稿。同時，IMPACT 開放多項贊助辦法，提供廠商在此國際盛會中嶄露頭角的機會，並協助大會共同提升節目品質。詳細贊助辦法與邀稿內容請參考大會網站(www.impact.org.tw)或秘書處楊小姐
歡迎各界踴躍支持，把握在此國際平台中發表論文、發揮廣告效益的機會，同時展現台灣的研發實力與企業精神。
CALL FOR PAPER

IMPACT 2010 as the fifth conference, jointly organized by IEEE CPMT-Taipei, ITRI, IMAPS-Taiwan, National Tsing Hua University, SIPO and TPCA, points the theme that Embrace IMPACT, Create Possibilities to bring together researchers, engineers and experts actively engaged in such a distinguished gathering. With the approach of recovery, such a great event looks forward to your paper to trigger off global impact on the earth.

Website: www.impact.org.tw

Important Dates

<table>
<thead>
<tr>
<th>Item</th>
<th>Date</th>
<th>Remark</th>
</tr>
</thead>
<tbody>
<tr>
<td>Abstract Submission</td>
<td>June 11, 2010</td>
<td>400-500 words</td>
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<td>Submit on-line through conference website</td>
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<tr>
<td>Abstract Acceptance Notification</td>
<td>July 15, 2010</td>
<td>Notice sent via email</td>
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<tr>
<td>Full Paper Submission (Camera-ready Version)</td>
<td>August 31, 2010</td>
<td>4 pages including figures and tables</td>
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<td>Submit on-line through conference website</td>
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<tr>
<td>Presentation Material Submission (Oral Presentation)</td>
<td>October 1, 2010</td>
<td>15 minutes presentation plus 5 minutes Q&amp;A (Totals to 20 minutes)</td>
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Scope of Paper Solicited (click for more details)

<table>
<thead>
<tr>
<th>Microsystems &amp; Packaging Technology</th>
<th>Electronic Circuit(PCB) &amp; Assembly Technology</th>
</tr>
</thead>
<tbody>
<tr>
<td>P2. Advanced Packaging Technologies</td>
<td>B2. Test, Quality, Inspection and Reliability Technology</td>
</tr>
<tr>
<td>P3. Interconnections &amp; Nanotechnology</td>
<td>B3. Build-up/HDI and Embedded Technology</td>
</tr>
<tr>
<td>P5. Thermal Management</td>
<td>B5. Surface Mounting and Assembly Technology</td>
</tr>
</tbody>
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★Papers focused on above scopes are encouraged to submit but it is not limited to this list.

Date: Wednesday-Friday, October 20-22, 2010

IMPACT 2010
Taipei Nangang Exhibition Center on Oct 20-22
Website: www.impact.org.tw
5th International Microsystems, Packaging, Assembly and Circuits Technology
Venue: Taipei Nangang Exhibition Center, Taiwan

Conference: IMPACT 2010

Exhibition: TPCA Show 2010

Organizer

- IEEE COMPONENTS, PACKAGING, & MANUFACTURING TECHNOLOGY SOCIETY (IEEE CPMT-Taipei)
- INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE, TAIWAN (ITRI)
- INTERNATIONAL MICROELECTRONICS AND PACKAING SOCIETY -TAIWAN (IMAPS-Taiwan)
- NATIONAL TSING HUA UNIVERSITY (NTHU)
- SEMICONDUCTOR INDUSTRY PROMOTION OFFICE (SIPO)
- TAIWAN PRINTED CIRCUIT ASSOCIATION (TPCA)

Co-Organizer

- I-SHOU UNIVERSITY (ISU)
- SURFACE MOUNT TECHNOLOGY ASSOCIATION (SMTA)
- TAIWAN PCB INSTITUTE
- TAIWAN THERMAL MANAGEMENT ASSOCIATION (TTMA)

IMPACT Secretariat
Taiwan Printed Circuit Association (TPCA)

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